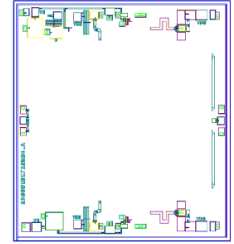


## AMT1110 8 – 12GHz Power Amplifier Chip



### Key Features :

- Frequency range : 8 – 12GHz
- Typical small signal gain : 23dB
- Typical output power : 41dBm
- Typical power added efficiency (PAE) : 40%
- Voltage bias : 8V, -0.75V
- Chip dimensions : 3.6mm x 4.0mm x 0.1mm
- Applications : wireless communication, transceiver module, radio telecommunication etc.

### Description :

AMT1110 chip is a Gallium Arsenide (GaAs) designed power amplifier chip, it uses dual voltage operation, with drain voltage  $V_{ds}$  at 8.0V, it offers 41dBm power output in a frequency range of 8 – 12GHz, power gain is 18.5dB. This chip is designed with ground through metal vias on the back technology. All chip products are 100% RF tested.

### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

Symbol	Parameter	Value	Remark
Vd	Drain Voltage	9V	
Id	Drain Current	6A	
Vg	Gate Voltage	-0.45V	
Ig	Gate Current	100mA	
Pd	Power Dissipation	45W	
Pin	Input Signal Power	25dBm	
Tch	Operating Temperature	150°C	
Tm	Sintering Temperature	310°C	30s, N <sub>2</sub> protection
Tstg	Storage Temperature	-65 ~ +150°C	

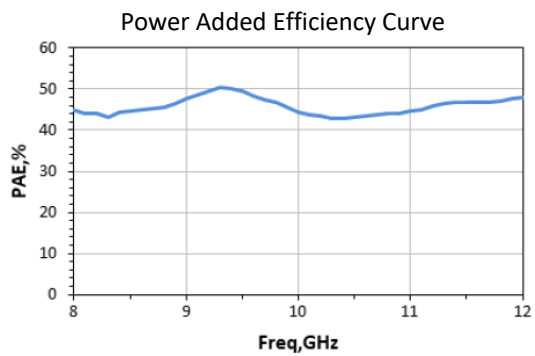
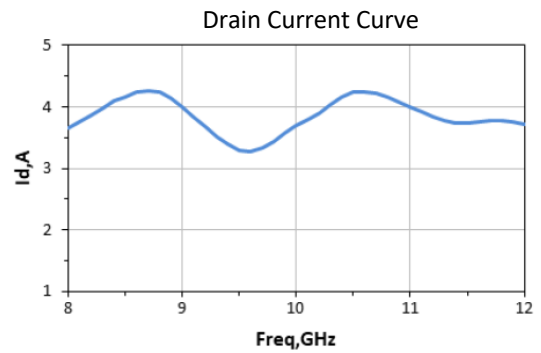
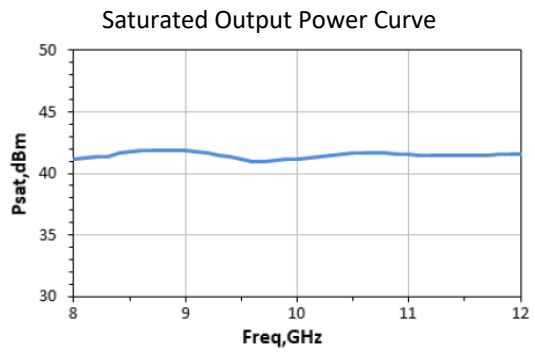
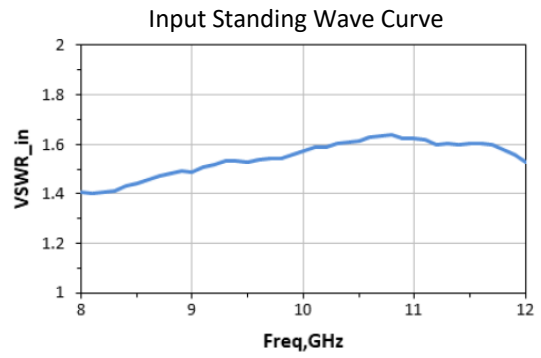
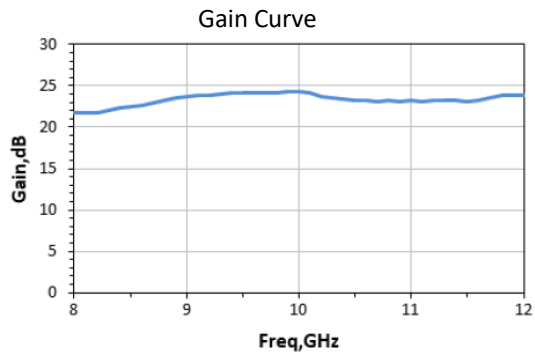
[1] Operation outside any of the Absolute Maximum Ratings may cause permanent device damage.

### Electrical Characteristics ( $T_a = 25^\circ\text{C}$ )

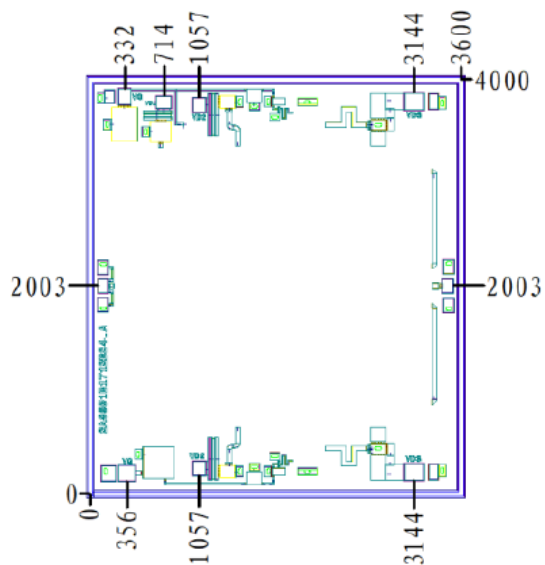
Symbol	Parameter	Test Condition	Value			Unit
			Min	Typical	Max	
G	Small Signal Gain	Vd = 8.0V Vg = -0.75V F : 8 ~ 12GHz	-	23	-	dB
Gp	Power Gain		-	18.5	-	dB
Pout	Saturated Power Output		-	41	-	dBm
PAE	Power Added Efficiency		-	40	-	%
VSWR_in	Input Standing Wave		-	1.6	-	

Note, no CW operation.

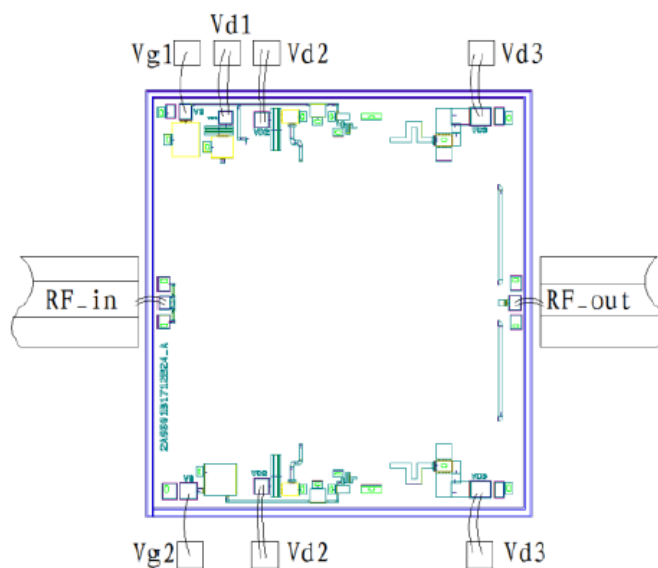
### Typical Performance



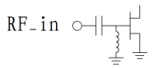
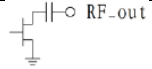
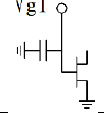
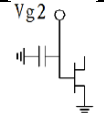
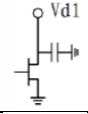
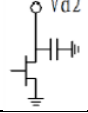
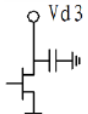
### Chip Dimensions (Unit : $\mu\text{m}$ )



### Chip Layout Diagram



### Pad Definition

Symbol	Function	Dimension	Equivalent Circuit
RF_in	RF signal input port, connecting to external 50Ω system. DC blocking capacitor is needed, if external DC current is applied to this pad.	100*128μm <sup>2</sup>	
RF_out	RF signal output port, connecting to external 50Ω system, no need to add DC blocking capacitor.	110*138μm <sup>2</sup>	
Vg1	Amplifier gate bias, need external 100pF, 1000pF capacitor.	125*154μm <sup>2</sup>	
Vg2	Amplifier gate bias, need external 100pF, 1000pF capacitor.	160*160μm <sup>2</sup>	
Vd1	Amplifier drain bias, need external 100pF, 1000pF capacitor.	143*118μm <sup>2</sup>	
Vd2	Amplifier drain bias, need external 100pF, 1000pF capacitor.	128*143μm <sup>2</sup>	
Vd3	Amplifier drain bias, need external 100pF, 1000pF capacitor.	200*160μm <sup>2</sup>	

Please see Appendix A for details.